



CALL FOR PAPERS

THIRD INTERNATIONAL SYMPOSIUM ON ADHESION ASPECTS OF THIN FILMS (INCLUDING ADHESION MEASUREMENT AND METALLIZED PLASTICS)

To be held November 7-9, 2007 in Orlando, Florida, USA

This symposium is the third in a series dealing with adhesion aspects of thin films, adhesion measurement and metallized plastics. The first symposium with this title was held in Orlando, FL in 2003 with the intent of integrating key aspects of three separate symposia which treated these topics singly in the past. The main idea was to provide a broader venue for the discussion and exploration of these three closely related fields of endeavor. The main part of the symposium focuses on those aspects of thin film technology that have a direct bearing on film adhesion to the substrate. This is a topic of both fundamental interest to all aspects of thin film technology and of great practical concern in applications where films of high stress are involved. The coating of diamond films onto machine tools is one of many applications where thin film adhesion is a critical factor in coating durability. The second part of the symposium will deal with the ability to accurately measure the adhesion of coatings to surfaces. This is always a crucial part of development and manufacturing processes dealing with coatings and films. Finally, metallized plastics are a burgeoning technology

heavily dependent on thin film adhesion with applications ranging from decorative design to optical coatings to advanced thin film wiring schemes in the microelectronics industry. Metallized plastic films allow the technologist to capitalize on the favorable properties of two disparate classes of materials to create new and unique products which transcend the performance and usefulness that can be obtained by either class alone.

The invited speakers have been selected so as to represent widely differing disciplines and interests, and they hail from academic, governmental and industrial research laboratories. This meeting is planned to be a truly international event both in geographic coverage as well as in spirit. The technical program will contain both invited overviews and contributed original research papers.

TOPICS OF INTEREST INCLUDE:

Adhesion Aspects of Thin Films

- ▶ Factors influencing adhesion - Residual stress, mechanical properties, contamination ... etc.
- ▶ Long term bond durability, corrosion prevention
- ▶ Adhesion promoters

Fundamental Issues

- ▶ Role of surface chemistry, wettability and morphology
- ▶ Fundamental adhesion mechanisms including role of surface roughness/morphology and film/substrate interactions

Applications of Adhesion Measurement

- ▶ Adhesion measurements in quality control and manufacturing
- ▶ Adhesion measurements in support of coating process research and development
- ▶ Adhesion measurement instrumentation for laboratory and manufacturing environments

Fundamental Aspects of Adhesion Measurement

- ▶ Mechanics of adhesion testing, the role of film stresses
- ▶ Fracture mechanics of adhesion testing
- ▶ Physico-chemical aspects of adhesion testing, the role of film morphology and chemistry

Metallized Plastics

- ▶ Metallization techniques and properties of metal deposits
- ▶ Metal diffusion during deposition
- ▶ Morphology and properties of metal deposits

Investigation of Interfacial Interactions

- ▶ Influence of polymer surface functional groups
- ▶ Metal-polymer interactions
- ▶ Fundamental adhesion mechanisms including coating-substrate interactions at nanoscale

This symposium is being organized by MST Conferences, LLC under the direction of Dr. K. L. Mittal, Editor, Journal of Adhesion Science and Technology. An archival volume is planned for this symposium and further details will be provided in due course. Please notify the conference chairman of your intention to present a paper as early as possible. An abstract of about 200 words should be sent by **September 15, 2007** to the conference chairman by any of the following methods:

E-mail: rhl@mstconf.com

FAX: 212-656-1016

Regular mail:

Dr. Robert H. Lacombe
Conference Chairman
3 Hammer Drive
Hopewell Junction, NY 12533

Contact by phone: 845-897-1654;
845-227-7026

Full conference details and registration via the Internet will be maintained on our web site:

www.mstconf.com/adhfilm2007.htm)

Or mail response form below to the conference chairman at the address above.

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